

WAFER BACK SURFACE TREATING METHOD AND DICING SHEET
ADHERING APPARATUS
Yoji OKAWA
Appl. No.: Unknown Atty Docket: UNIU79.022AUS

FIG. 1

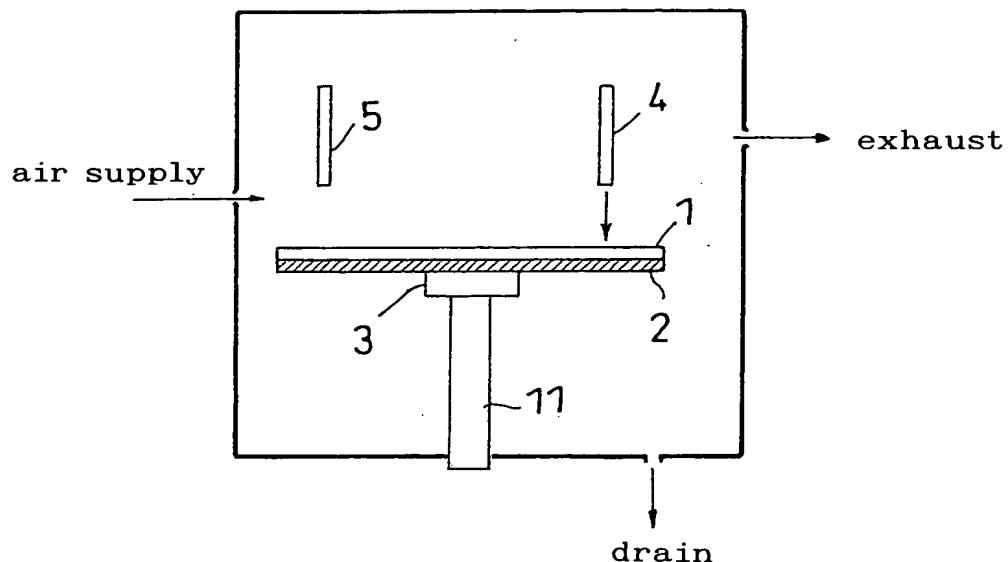
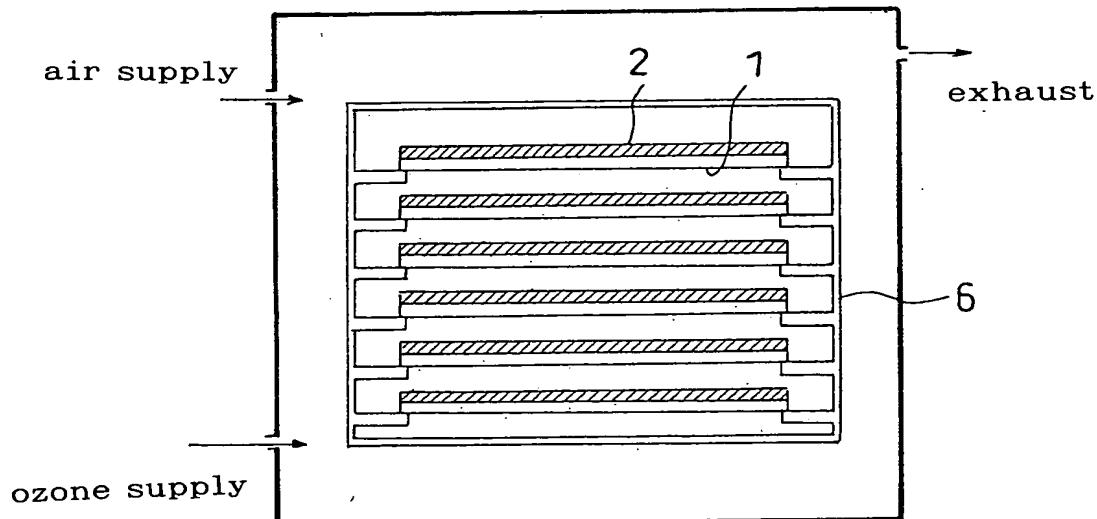


FIG. 2



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FIG.3

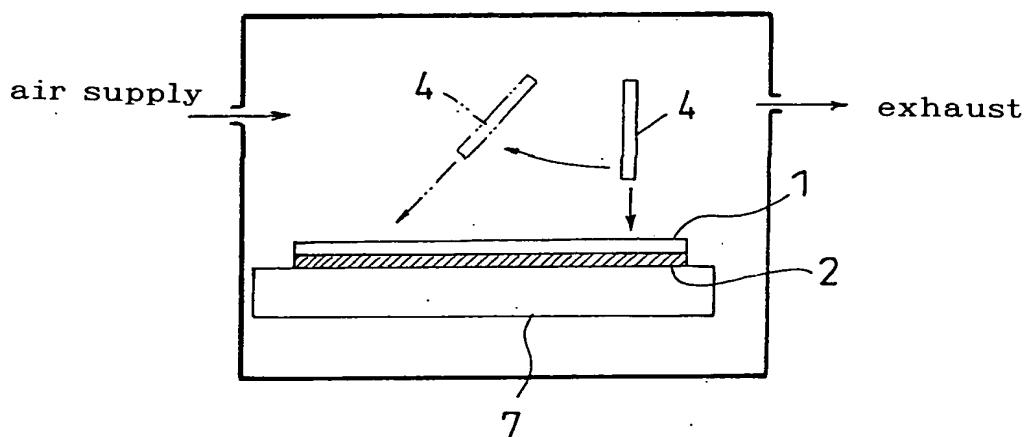
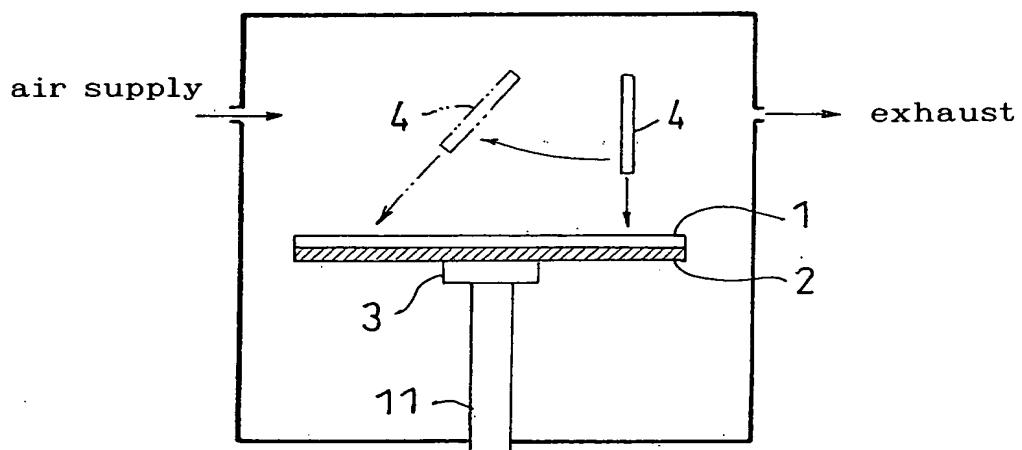


FIG.4



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FIG. 5

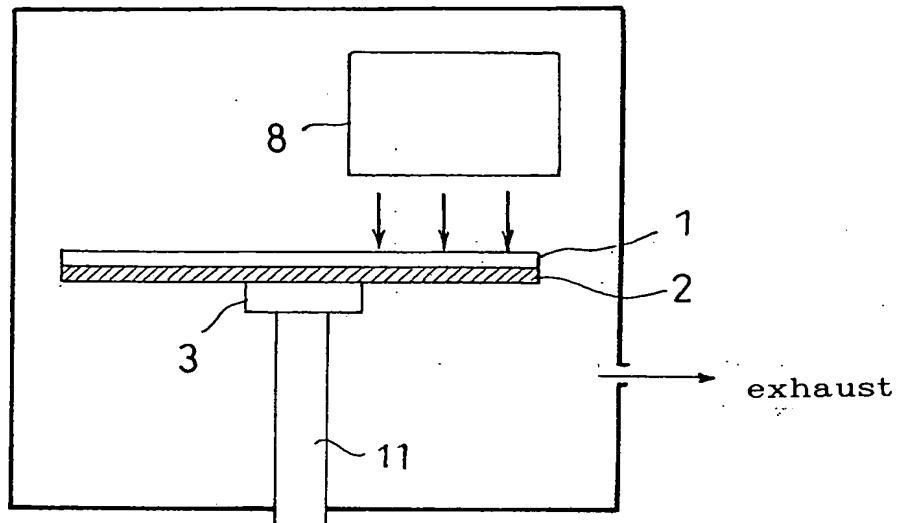


FIG. 6

